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TITLE: EPOXY RESIN COMPOSITION FOR SEALING

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INVENTOR-INFORMATION:

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ABSTRACT:

PURPOSE: To obtain the title composition which is equivalent to the conventional solid epoxy resin composition in the reliability of a sealed semiconductor and is equivalent to the conventional two-pack epoxy resin composition in sealing workability, by mixing an epoxy resin with a specified curing agent, a surfactant and a filler.

CONSTITUTION: To 100pts.wt. liquid epoxy resin, a mixture of 1∼8pts.wt. at least one curing agent selected from among imidazole compounds of formulas I and II (wherein m is 1∼14, n is 0∼2, R1∼3 are each H, alkyl, or phenyl, R4 is H, methyl, hydroxymethyl and R5 is alkyl or phenyl) with 0.001∼1pt.wt. fluorine-containing surfactant and 50∼80wt% filler (e.g., crystalline silica) treated with a titanate-containing coupling agent [e.g., tetraisopropylbis(dioctyl phosphite) titanate] are added.

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